

March	June	September	December
2017/02/20 2017/02/25 2017/03/01	2017/05/20 2017/05/25 2017/06/01	2017/08/20 2017/08/25 2017/09/01	2017/11/20 2017/11/25 2017/12/01
Tech Investment			
把脉中国半导体发展之道	创新元素探究	技术与资本的碰撞	人工智能：资本的猎物
Year Book 2017	Feature		
Industry Outlook 产业展望	Automotive electronics 汽车电子	Intelligent Robot 智能机器人	Pure electric car 纯电动汽车
Wafer Fabrication			
Intelligent manufacturing 智能制造	Power Device 功率器件	Wafer Cleaning Technology 晶圆清洗技术	IoT IC工艺 IoT IC Process
Packaging & Testing			
SEMI Source	SIP Packaging 系统级封装	Wafer-Level Package 晶圆级封装	New Electronic Assembly 电子组装封装新技术
e-Newsletter			
SEMI China Daily News	IC APP;	eCarChina;	Show Daily during the SEMICON China

AD.Type	Dimension width*height(mm)	File size	Format	1x(\$)	3x(\$)	4x(\$)
1	Full Page 200*267	>300dpi	JPEG / PDF / EPS	3,200	2,600	2,000
2	1/2 Page 200*134 (horz.,vert.,or island)	>300dpi	JPEG / PDF / EPS	1,920	1,560	1,200
3	Cover Two Spread 400*267 (inside front cover and page1)	>300dpi	JPEG / PDF / EPS	7,000	5,600	4,300
4	Cover Two 200*267 (inside front cover)	>300dpi	JPEG / PDF / EPS	4,000	3,200	2,400
5	Cover Three 200*267 (inside back cover)	>300dpi	JPEG / PDF / EPS	4,000	3,200	2,400
6	Cover Four 200*267 (back cover)	>300dpi	JPEG / PDF / EPS	4,900	4,000	3,000

\* Please allow 3mm bleeds. Color model: CMYK

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